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the one-time programmable link, where it is coupled to a power package as recited in claim

1. *Chrysomelidae* (10 species)
 2. *Curculionidae* (10 species)
 3. *Chrysomelidae* (10 species)
 4. *Curculionidae* (10 species)
 5. *Chrysomelidae* (10 species)
 6. *Curculionidae* (10 species)
 7. *Chrysomelidae* (10 species)
 8. *Curculionidae* (10 species)
 9. *Chrysomelidae* (10 species)
 10. *Curculionidae* (10 species)

1 9. The package as recited in claim 2 wherein the second end of the
2 programmable element is coupled to an external package connection and to an

3 internal package node that couples to an input terminal of the integrated circuit die
4 when the integrated circuit die is mounted.

1 10. The package as recited in claim 2 wherein the programmable element
2 is programmable using a laser.

1 11. The package as recited in claim 2 wherein the programmable element
2 is programmable using an electrical current.

Sub B4 1 12. The package as recited in claim 2 further comprising another
2 programmable element coupled between the second end of the programmable element
3 and an external package connection.

1 13. The package as recited in claim 1 further comprising a second one-
2 time programmable element coupled in parallel with the one time programmable
3 element and wherein the one one-time programmable element is a fuse and the second
4 one-time programmable element is an antifuse.

Sub B4 1 14. The package as recited in claim 2 wherein the package includes
2 at least one pair of programmable elements, the one pair including the one
3 one-time programmable element and a second one-time programmable
4 element, the second one-time programmable element having a first and
5 second end, the first end of the second one-time programmable
6 element coupled to a second power supply voltage node and the second
7 end of the second one-time programmable element being coupled
8 through an internal package node to the second end of the first one-
9 time programmable element.

Sub B5 1 15. The package as recited in claim 14 wherein the internal package node
2 is coupled to at least one of an external package connection and an input terminal of
3 the integrated circuit die, after mounting of the integrated circuit die.

1 16. The package as recited in claim 14 further comprising a first resistive
2 element coupled between the internal package node and the power supply node and a

23. The electronic device as recited in claim 17 wherein the package is a multi-layered package and the programmable element is located on a layer other than the surface of the package.

24. The electronic device as recited in claim 17 wherein the one or more programmable elements, when programmed, specify a control value relating to clock frequency at which the processor operates.

25. The electronic device as recited in claim 17 wherein a state of the programmable element specifies use of error correction code (ECC) for a cache memory on the processor.

26. The electronic device as recited in claim 17 wherein the one one-time programmable element is part of a one-time programmable element pair, the programmable element pair including a second one-time programmable element in addition to the one one-time programmable element, the second programmable element having a first end coupled to the internal package node and a second end coupled to a second power supply voltage.

27. The electronic device as recited in claim 26 further comprising a first resistive element coupled respectively between the internal package node and the first power supply node and a second resistive element coupled between the internal package node and the second power supply node, thereby providing a voltage divider when the first power supply node is electrically coupled to the second power supply node through the programmable element pair.

28. A method for setting a parameter value for an integrated circuit, comprising:
selectively programming one or more one-time programmable elements located on an integrated circuit package, thereby selectively coupling an internal package node to a supply voltage node.

29. The method as recited in claim 28 wherein the one-time programmable elements are one of a fuse and an antifuse.

1 30. The method as recited in claim 29 wherein the internal package node
2 couples to at least one of an external package connection and an input contact of an
3 integrated circuit die.

1 31. The method as recited in claim 29 wherein the specifies an operating
2 voltage for at least a portion of the integrated circuit.

1 32. The method as recited in claim 29 wherein an integrated circuit die is
2 mounted on the package when the one or more one-time programmable elements are
3 being selectively programmed.

1 33. A method comprising:
2 selectively programming a first programmable element of a programmable
3 element pair located on an integrated circuit package to selectively
4 couple an internal node to a first power supply voltage; and
5 selectively programming a second programmable element of the
6 programmable element pair to selectively couple the internal node to a
7 second power supply voltage.

1 34. The method as recited in claim 33 wherein the internal node is coupled
2 to at least one of an external package connection and an input terminal of an
3 integrated circuit die mounted in the integrated circuit package.

1 35. The method as recited in claim 33 wherein the first power supply
2 voltage is ground (Vss).

1 36. The method as recited in claim 33 wherein the second power supply
2 voltage is Vcc.

1 37. An apparatus comprising:
2 a semiconductor package; and
3 means for specifying a parameter value for the apparatus.

1 38. The apparatus as recited in claim 37 further comprising a processor
2 mounted in the semiconductor package.

2 mounted in the semiconductor package.

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